

## PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>YASUCHIKA HASEGAWA</td> <td>09/17/2013</td> </tr> <tr> <td>MASASHI MAEDA</td> <td>09/28/2013</td> </tr> <tr> <td>MINA KUMAGAI</td> <td>09/22/2013</td> </tr> <tr> <td>KOJI FUSHIMI</td> <td>09/27/2013</td> </tr> </tbody> </table>		Name	Execution Date	YASUCHIKA HASEGAWA	09/17/2013	MASASHI MAEDA	09/28/2013	MINA KUMAGAI	09/22/2013	KOJI FUSHIMI	09/27/2013
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CORRESPONDENCE DATA											
<p>Fax Number: (202)293-7860</p> <p>Phone: 202-293-7060</p> <p>Email: mdelozier@sughrue.com, sughrue@sughrue.com</p> <p><i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i></p> <p>Correspondent Name: SUGHRUE MION, PLLC</p> <p>Address Line 1: 2100 PENNSYLVANIA AVENUE, N.W.</p> <p>Address Line 2: SUITE 800</p> <p>Address Line 4: WASHINGTON, DISTRICT OF COLUMBIA 20037</p>											
ATTORNEY DOCKET NUMBER:	Q206625										
NAME OF SUBMITTER:	MICHELLE L DELOZIER FOR ABRAHAM J ROSNER										

Signature:	/Michelle L Delozier/
Date:	11/20/2013
Total Attachments: 1 source=Q206625ASSIGNMENT#page1.tif	

**ASSIGNMENT**

Whereas, I/we,

NameAddress1) **Yasuchika HASEGAWA**c/o NATIONAL UNIVERSITY CORPORATION HOKKAIDO UNIVERSITY,  
Kita 8-jo Nishi 5-chome, Kita-ku,  
Sapporo-shi, Hokkaido 060-0808 Japan2) **Masashi MAEDA**c/o NATIONAL UNIVERSITY CORPORATION HOKKAIDO UNIVERSITY,  
Kita 8-jo Nishi 5-chome, Kita-ku,  
Sapporo-shi, Hokkaido 060-0808 Japan3) **Mina KUMAGAI**c/o NATIONAL UNIVERSITY CORPORATION HOKKAIDO UNIVERSITY,  
Kita 8-jo Nishi 5-chome, Kita-ku,  
Sapporo-shi, Hokkaido 060-0808 Japan4) **Koji FUSHIMI**c/o NATIONAL UNIVERSITY CORPORATION HOKKAIDO UNIVERSITY,  
Kita 8-jo Nishi 5-chome, Kita-ku,  
Sapporo-shi, Hokkaido 060-0808 Japan

hereinafter called assignor(s), have invented certain improvements in

**THIN FILM AND NANOCRYSTALS OF EUROPIUM (II) COMPOUND DOPED WITH METAL IONS**

and executed an application for Letters Patent of the United States of America therefor on even date herewith unless otherwise indicated below:

filed on September 3, 2013, Serial No. 14/002895; and

Whereas

NATIONAL UNIVERSITY CORPORATION HOKKAIDO UNIVERSITY

Kita 8-jo Nishi 5-chome, Kita-ku,

Sapporo-shi, Hokkaido 060-0808 Japan

(assignee), desires to acquire the entire right, title and interest in the application and invention, and to any United States patents to be obtained therefor;

NOW THEREFORE, be it known that, for good and valuable consideration from assignee, the receipt of which is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and

INVENTORSDATE SIGNED

1):

Name :

Yasuchika Hasegawa  
Yasuchika HASEGAWASep. 17, 2013

2):

Name :

Masashi Maeda  
Masashi MAEDASep. 28, 2013

3):

Name :

Mina Kumagai  
Mina KUMAGAISep. 22, 2013

4):

Name :

Koji Fushimi  
Koji FUSHIMISep. 27, 2013